

SOT908-3

plastic thermal enhanced very thin small outline package; no leads; 8 terminals

8 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|--|
| Terminal position code | D (double) |
| Package type descriptive code | HVSON8 |
| Package type industry code | HVSON8 |
| Package style descriptive code | HVSON (thermal enhanced very thin small outline; no leads) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| IEC package outline code | --- |
| JEDEC package outline code | MO-229 |
| JEITA package outline code | --- |
| Mounting method type | S (surface mount) |
| Issue date | 23-12-2011 |

Table 1. Package summary

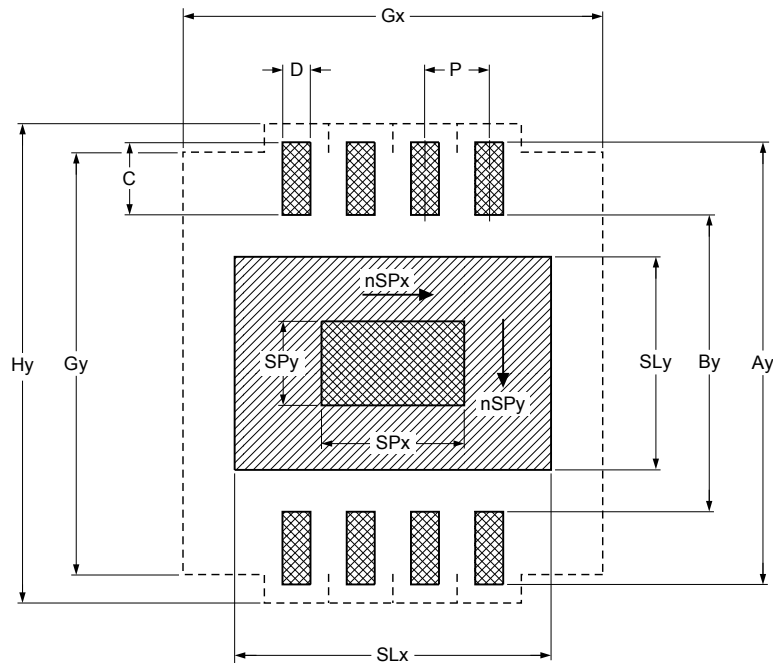
| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D | package length | 2.9 | - | 3 | 3.1 | mm |
| E | package width | 2.9 | - | 3 | 3.1 | mm |
| A | seated height | 0.8 | - | 0.85 | 1 | mm |
| e | nominal pitch | - | - | 0.5 | - | mm |
| n ₂ | actual quantity of termination | - | - | 8 | - | |






3. Soldering

Footprint information for reflow soldering of HVSON8 package

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-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area

DIMENSIONS in mm

| P | Ay | By | C | D | SLx | SLy | SPx | SPy | Gx | Gy | Hy |
|-----|------|------|-----|------|------|------|-----|------|------|------|-----|
| 0.5 | 3.45 | 2.25 | 0.6 | 0.25 | 2.45 | 1.65 | 1.1 | 0.65 | 3.25 | 3.25 | 3.7 |

| nSPx | nSPy |
|------|------|
| 1 | 1 |

Issue date 12-07-03
12-07-12

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Fig. 2. Reflow soldering footprint for HVSON8 (SOT908-3)

4. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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